

MATERIAL DECLARATION



Material Number	CRL0805 series			
Product Line	Thick Film Low Ohmic Chip Resistors			
Compliance Date	2017/6/5			
RoHS Compliant	YES	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.0043388	Aluminum oxide	1344-28-1	96.0%	78.83520	82.12
				Quartz	14808-60-7	4.0%	3.28480	
2	Conductor Layer	Ink	0.00011518	Nickel	7440-02-0	95.0%	2.07100	2.18
				Glass	65997-17-3	5%	0.10900	
3	Resistive Element	Ink	0.0001891	Manganese	7439-96-5	10%	0.36	3.58
				Copper	7440-50-8	60%	2.15	
				Nickel	7440-02-0	30%	1.07	
4	Over-Coating	Epoxy	0.0000861	Epoxy	25068-38-6	100%	1.63000	1.63
5	Marking	Epoxy	0.0000127	Epoxy	25085-99-8	100%	0.24000	0.24
6	End Terminal	Nickel-Chromium	0.00001110	Nickel	7440-02-0	80%	0.16800	0.21
				Chromium	7440-47-3	20%	0.04200	
7	Plating Layer	Copper	0.0002948	Copper	7440-50-8	100%	5.58000	5.58
		Nickel	0.0001178	Nickel	7440-02-0	100%	2.23000	2.23
		Tin	0.0001178	Tin	7440-31-5	100%	2.23000	2.23
		Total weight	0.005282					

This Document was updated on: 2017/06/05

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.